

WHAT IS CLAIMED IS:

[1] A method for manufacturing coated chip-like optical parts,
comprising the steps of:

coating a first multi-layer coat on a first coat depositing surface
5 on one side of a thickened substrate;

slitting said first multi-layer coat in a lattice-like pattern and to a
depth corresponding to thickness of said first multi-layer coat to divide
same into square subdivisions in a unit size of coated chip-like optical
parts to be produced;

10 grinding a surface on the other side of said thickened substrate
to obtain a parental substrate material of a reduced thickness;

depositing a second multi-layer coat on a second coat depositing
surface on a ground side of said parental substrate material; and

cutting said parental substrate material into units of coated chip-
15 like optical parts of ultimate products;

said thickened substrate being initially allotted with a sufficient
thickness to prevent deformations caused by deposition of said first
multi-layer coat, and later ground down to a reduced thickness
sufficient for precluding possibilities of deformations and damages as
20 caused under the influence of stress imposed by slitted subdivisions of

said first multi-layer coat.

[2] A method for manufacturing coated chip-like optical parts as defined in claim 1, wherein said first and second multi-layer coats are optical coats different from each other in optical properties.

5 [3] A method for manufacturing coated chip-like optical parts as defined in claim 1, wherein both of said first and second multi-layer coats are optical multi-layer coats, said second optical multi-layer coat being deposited in a number of layers suitable for substantially canceling stress imposed by slitted subdivisions of said first optical
10 multi-layer coat and adapted to generate aimed optical properties in cooperation with said first optical multi-layer coat.